

N-Channel 30V(D-S) MOSFET

Product summary

V_{DS}	30	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	8	m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	10	m Ω
I_D ($T_C=25^{\circ}C$)	30	A

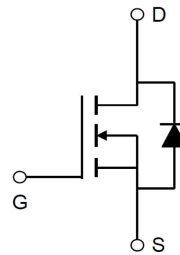
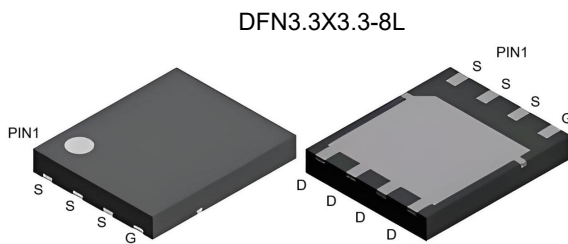
Features

- High density cell design for low $R_{DS(ON)}$
- Trench Power LV MOSFET technology

Applications

- Load switching
- High current load applications
- Uninterruptible power supply

Pin Configuration



Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAL30N03A	DFN3.3X3.3-8L	13"	3000pcs/5000pcs

Absolute Maximum Ratings (at $T_A=25^{\circ}C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current at $V_{GS}=10V$ ^A	$T_C=25^{\circ}C$	30
		$T_C=100^{\circ}C$	21
I_{DM}	Pulse Drain Current Tested ^B	115	A
E_{AS}	Single Pulse Avalanche Energy ^C	112	mJ
P_D	Power Dissipation	21	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +175	$^{\circ}C$

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to Case ^A	7.1	$^{\circ}C/W$

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
$R_{DS(ON)}$	Drain-Source On-State Resistance ^B	$V_{GS}=10V, I_D=15A$	--	8	10.5	m Ω
		$V_{GS}=4.5V, I_D=15A$	--	10	14	m Ω
V_{SD}	Forward Voltage	$I_S=15A, V_{GS}=0V$	--	--	1.2	V
I_S	Maximum Body-Diode Continuous Current		--	--	30	A
Dynamic Parameters ^D						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V$ $f=1\text{MHz}$	--	950	--	pF
C_{oss}	Output Capacitance		--	204	--	pF
C_{rss}	Reverse Transfer Capacitance		--	121	--	pF
Q_g	Total Gate Charge	$V_{DS}=15V, I_D=30A$ $V_{GS}=10V$	--	28	--	nC
Q_{gs}	Gate-Source Charge		--	7	--	nC
Q_{gd}	Gate-Drain Charge		--	5	--	nC
$t_{D(on)}$	Turn-on Delay Time	$V_{DS}=20V$ $I_D=2A, R_L=1\Omega,$ $V_{GS}=10V, R_{GEN}=3\Omega$	--	8	--	nS
t_r	Turn-on Rise Time		--	15	--	nS
$t_{D(off)}$	Turn-off Delay Time		--	27	--	nS
t_f	Turn-off Fall Time		--	7	--	nS

A. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

B. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

C. The EAS data shows Max. rating . The test condition is $V_{DD}=20V, V_{GS}=10V, L=0.5mH, R_g=25\Omega$.

D. Guaranteed by design, not subject to production testing.

Typical Characteristics

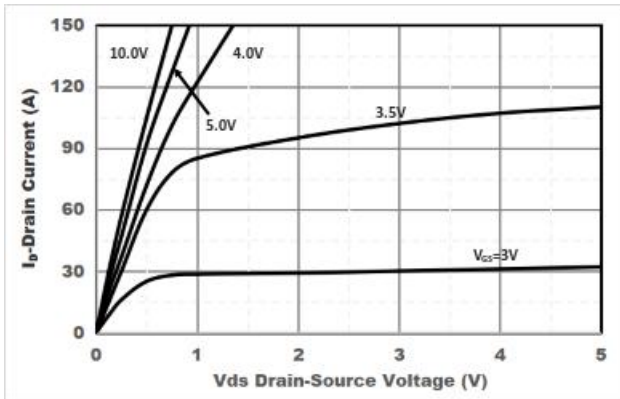


Figure1. Output Characteristics

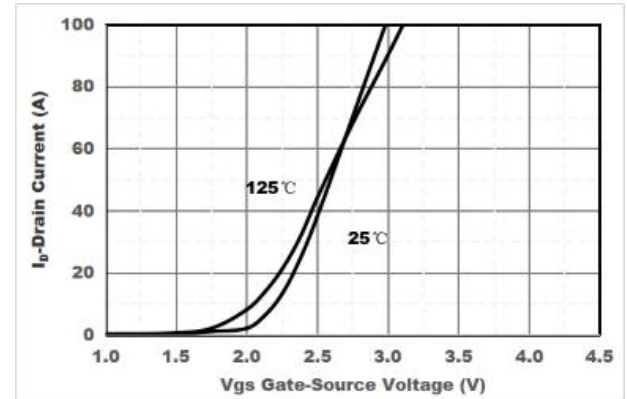


Figure2. Transfer Characteristics

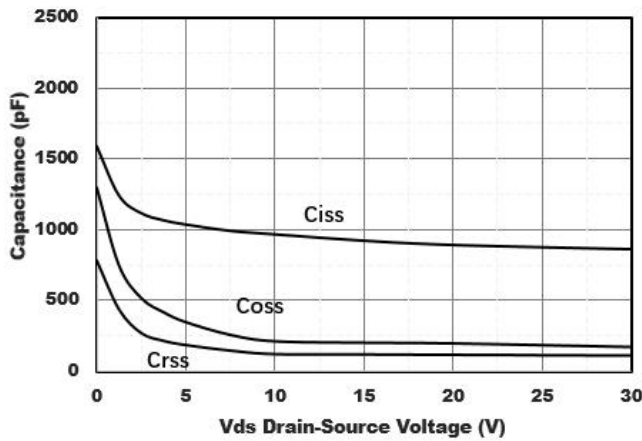


Figure3. Capacitance Characteristics

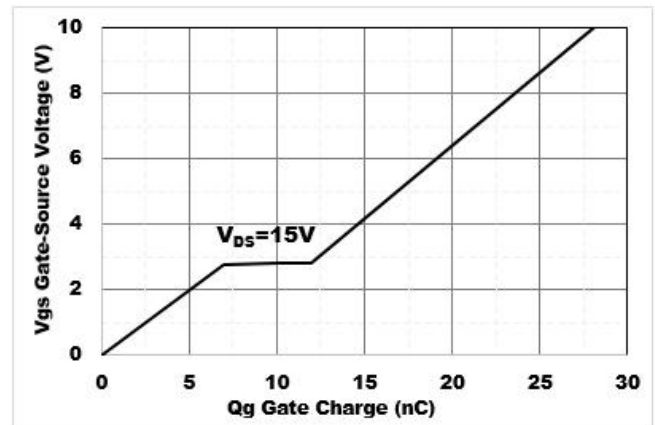


Figure4. Gate Charge

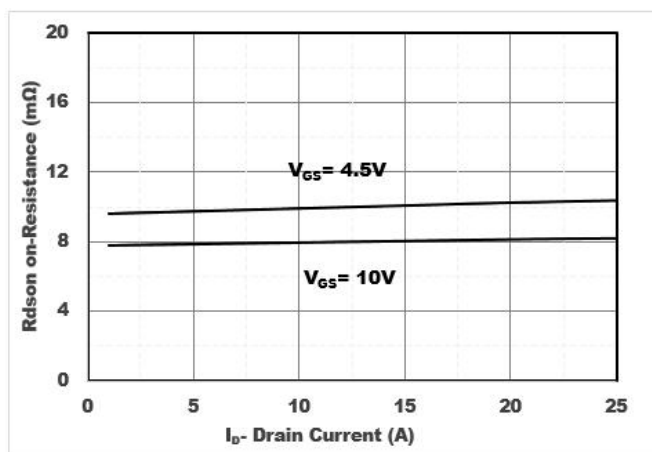


Figure5. Drain-Source on Resistance

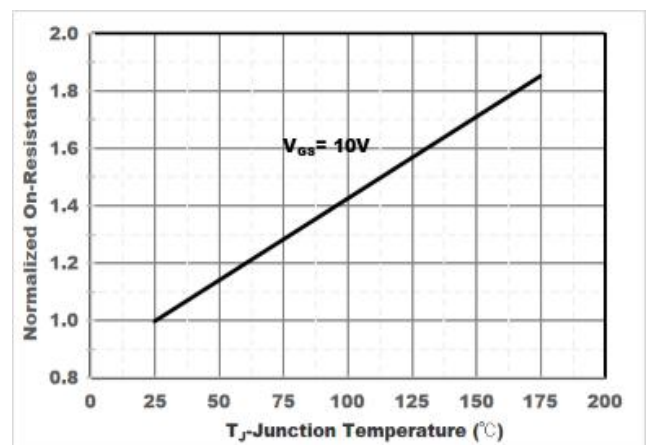


Figure6. Drain-Source on Resistance

Typical Characteristics

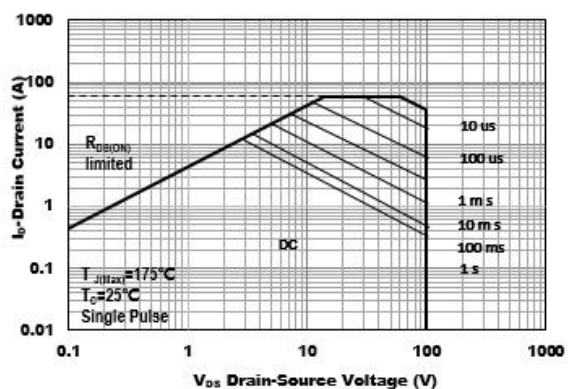


Figure7. Safe Operation Area

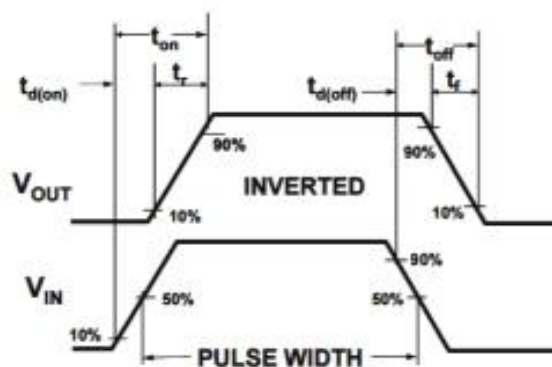


Figure8. Switching wave

Figure 1 consists of three diagrams illustrating the dimensions of the test specimen:

- (a) Top view: A rectangular plate with overall width B and overall height A . A green crosshair is centered on the plate.
- (b) Front view: A detailed view of the front face showing internal features. Dimensions include E (width of the central rectangular opening), D (height of the central rectangular opening), H (height of the top flange), F (height of the bottom flange), G (width of the bottom flange), and e (width of the bottom flange's internal features).
- (c) Side view: A detailed view of the side face showing the thickness of the plate. Dimensions include C (total thickness), $C1$ (thickness of the top flange), and $C2$ (thickness of the bottom flange).

A	B	C	C1
3.25±0.05	3.25±0.05	0.8±0.05	0.2±0.02
C2	D	E	F
0.05Max	1.9±0.1	2.35±0.15	0.45±0.05
G	H	e	
0.3±0.05	0.35±0.05	0.65±0.05	
单位: mm			